Product / Package Information

Package	TQFP_EP
Body Size (mm)	14 X 14 X 1.0 (6.1 EP)
Lead Count	100
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
JIG Material Content Compliant	Level A and B

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica fused	60676-86-0	2.89E-01	88	880000	57.00	570035
Thermosets	Epoxy & Phenol resin	Proprietary	3.78E-02	11.5	115000	7.45	74493
Other inorganic materials	Carbon black	1333-86-4	1.64E-03	0.5	5000	0.32	3239
Subtotal			3.28 E-01	100.00	1000000	64.78	647767

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.33E-01	97.5	975000	26.31	263062
Copper & its alloys	Iron	7439-89-6	3.21E-03	2.35	23500	0.63	6340
Copper & its alloys	Zinc	7440-66-6	1.64E-04	0.12	1200	0.03	324
Copper & its alloys	Phosphorus	7723-14-0	4.10E-05	0.03	300	0.01	81
Subtotal			1.37 E-01	100.00	1000000	26.98	269807

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Silver	7440-22-4	9.80 E-04	100.0	1000000	0.19	1933

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	8.56 E-03	100.0	1000000	1.69	16888

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	2.10 E-03	100.00	1000000	0.41	4143

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.52 E-02	100.0	1000000	4.97	49676

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Silver	7440-22-4	3.59E-03	72.40	724000	0.71	7085
Thermoset	Epoxy compound	Proprietary	8.98E-04	18.10	181000	0.18	1771
Other organic materials	Anhydrides	Proprietary	3.37E-04	6.79	67900	0.07	664
Other organic materials	Polymeric material	Proprietary	1.34E-04	2.71	27100	0.03	265
Subtotal	Subtotal		4.96 E-03	100.00	1000000	0.98	9785

	Weight (g)	Percentage (%)	PPM
Package Totals	**5.07 E-01**	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary